MICROWAVE POWER GaAs FET

Internally Matched Power GaAs FETs (X, Ku-Band)

Features

- High power
 - $P_{1dB} = 39.5 \text{ dBm}$ at 11.7 GHz to 12.7 GHz
- High gain
- G_{1dB} = 5.0 dB at 11.7 GHz to 12.7 GHz
 Broadband internally matched
- Hermetically sealed package

RF Performance Specifications ($T_a = 25^{\circ}C$)

| Characteristic | Symbol | Condition | Unit | Min. | Тур. | Max |
|---------------------------------------|------------------|---|------|------|------|-----|
| Output Power at 1dB Compression Point | P _{1dB} | V _{DS} = 9V f = 11.7 - 12.7 GHz | dBm | 38.5 | 39.5 | - |
| Power Gain at 1dB Compression Point | G _{1dB} | | dB | 4.0 | 5.0 | - |
| Drain Current | I _{DS} | | Α | - | 3.4 | 4.4 |
| Power Added Efficiency | η_{add} | | % | - | 20 | - |
| Channel-Temperature Rise | ΔT_{ch} | V _{DS} x I _{DS} x R _{th (c-c)} | °C | - | - | 80 |

Electrical Characteristics (T_a = 25°C)

| Characteristic | Symbol | Condition | Unit | Min. | Тур. | Max. |
|-------------------------------|-----------------------|--|------|------|------|------|
| Transconductance | gm | V _{DS} =3V I _{DS} = 4.0A | mS | - | 2400 | - |
| Pinch-off Voltage | V _{GSoff} | V _{DS} = 3V I _{DS} = 120 mA | V | -2 | -3.5 | -5 |
| Saturated Drain Current | I _{DSS} | V _{DS} = 3V V _{GS} = 0V | Α | - | 8.0 | 10.4 |
| Gate-Source Breakdown Voltage | V _{GSO} | I _{GS} = -120 μA | V | -5 | - | - |
| Thermal Resistance | R _{th (c-c)} | Channel to Case | °C/W | - | 1.6 | 2.5 |

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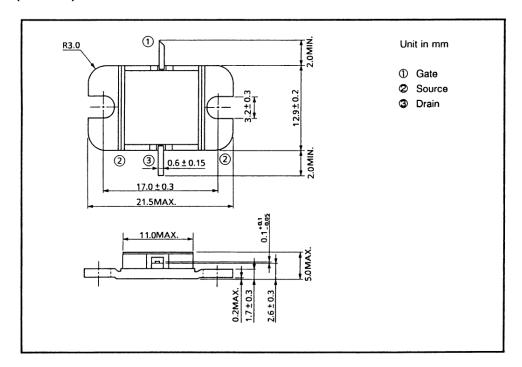
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Absolute Maximum Ratings ($T_a = 25^{\circ}C$)

| Characteristic | Symbol | Unit | Rating |
|---|------------------|------|-----------|
| Drain-Source Voltage | V _{DS} | V | 15 |
| Gate-Source Voltage | V _{GS} | V | -5 |
| Drain Current | I _D | Α | 10.4 |
| Total Power Dissipation (T _c = 25°C) | P _T | W | 60 |
| Channel Temperature | T _{ch} | °C | 175 |
| Storage Temperature | T _{stg} | °C | -65 ~ 175 |

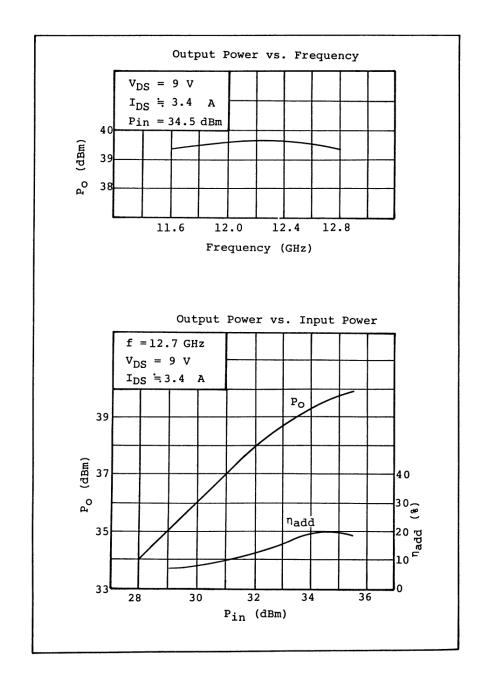
Package Outline (2-11C1B)



Handling Precautions for Packaged Type

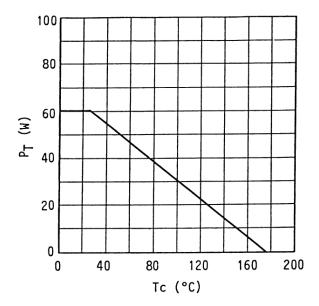
Soldering iron should be grounded and the operating time should not exceed 10 seconds at 260°C.

RF Performances



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Power Dissipation vs. Case Temperature



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